

Why need an adapter?

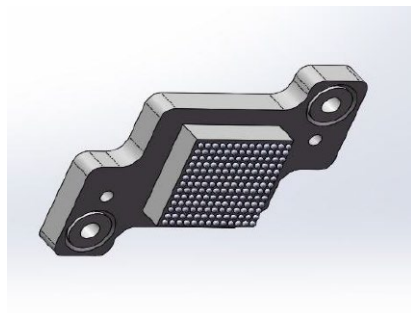
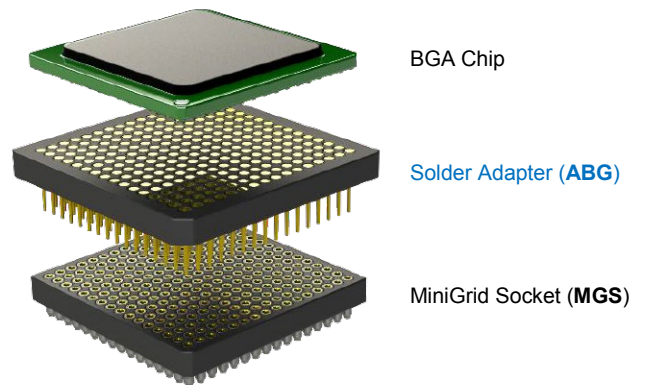
In certain cases, you are not able to place any test socket on your board, because:

- Its density is too high
- It was not designed to accommodate any test socket.
- The package dimensions or layout have changed.
- Etc...

So E-tec Interconnect has developed a mounting solution with adapter for Test Sockets. As usual, we propose a full range of mounting, to help customer to find the right solution for his own issue.

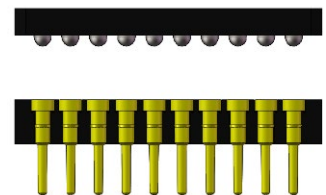
ABG series: Male adapter

The E-tec Interconnect BGA Adapter System comprises two elements, the BGA solder adapter onto which the BGA chip is soldered (converting the BGA chip to a PGA, **ABG** series), and the MiniGrid Socket which is soldered to the PCB. The solder adapter can then be plugged into the **MiniGrid Socket** (refer to **MGS** series).



The pitch becomes smaller and smaller. So, E-tec Interconnect modified the ABG series and reduce the pitch to 0.4 mm. Its design team also enhanced the functionality to incorporate from now on our Solderless Compression Test Socket as well.

Thanks to this progress, E-tec Interconnect continues to respond to your constant new requests.



Standard SMT pin, raised SMT pin and SMT solderballs are available in both functions.

E-tec Interconnect offers any pin-out, configuration and grid size.

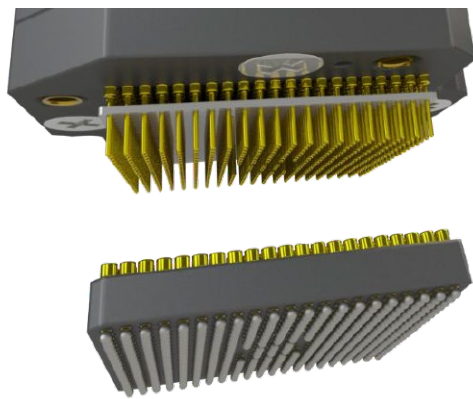
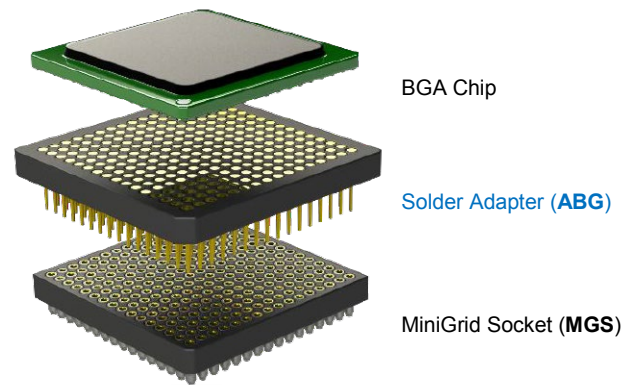
Special terminal designs are possible on request



MGS series: Female adapter

The E-tec Interconnect **MiniGrid Socket** adapter is soldered to the target board and is designed to accept the BGA solder **ABG** adapter (where the chip is soldered to the adapter board) or any kind of miniPGA or PGI.

As an alternative, this MiniGrid Socket is also designed to accept the “true” through hole BGA Sockets (where the chips can be socketed without soldering).

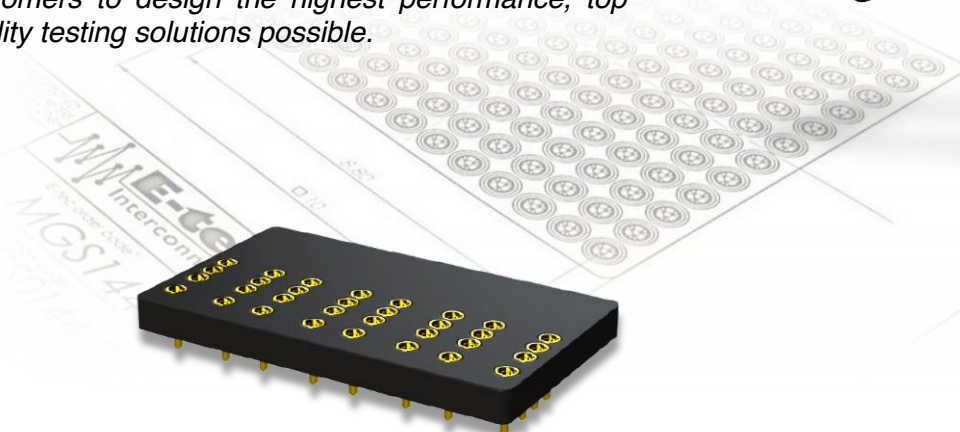
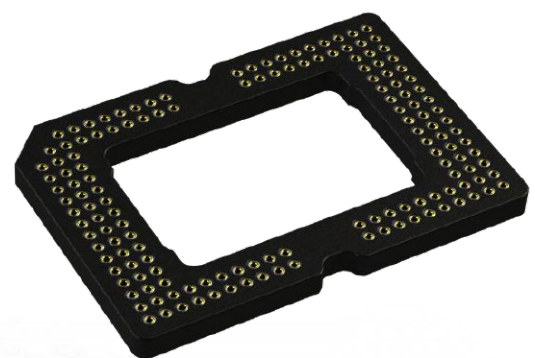


MiniGrid Socket adapter allows E-tec Interconnect Test Sockets to be inserted.

The SMT adapter is available either with solder ball or with solid pin terminals. This SMT adapter emulates the chip’s BGA footprint and is easily installed using standard flux and reflow techniques. The solder ball adapters have the same solder ball types as the IC’s they are emulating. You can combine the SMT foot with any of the E-tec Interconnect socket styles shown in the Test Socket section. The corresponding male BGA socket, through hole type, is plugged into the adapter.

E-tec Interconnect offer any pin-out, configuration and grid size for pitch 0.8mm, 1.00mm and 1.27mm, any pin-out, configuration and grid size. Other pitch and special terminal designs are possible on request.

E-tec Interconnect prides itself on being a leader in the Test Interconnect industry and working with our customers to design the highest performance, top quality testing solutions possible.



Pitch	Adapter series				
	MGS THT	MGS SMT Solderpin	MGS SMT Solderballs	ABG SMT Solderpin	ABG SMT Solderballs
0.4 mm	no	no	no	yes	yes
0.5 mm	no	no	no	yes	yes
0.8 mm	yes	yes	yes	yes	yes
1.0 mm	yes	yes	yes	yes	yes
1.27 mm	yes	yes	yes	yes	yes

